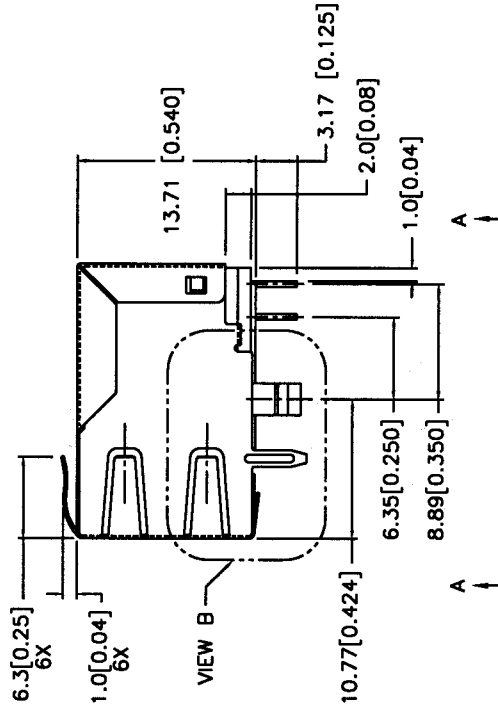
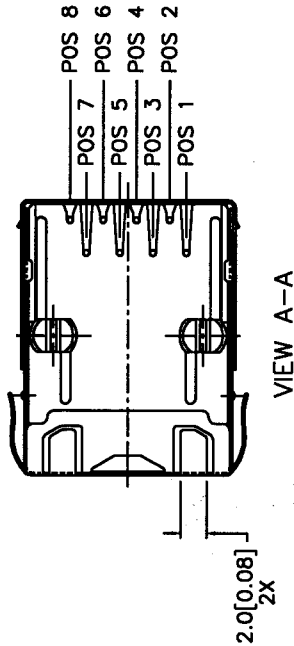
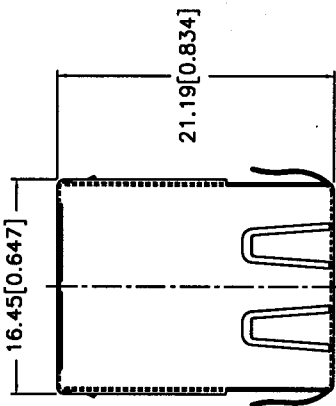
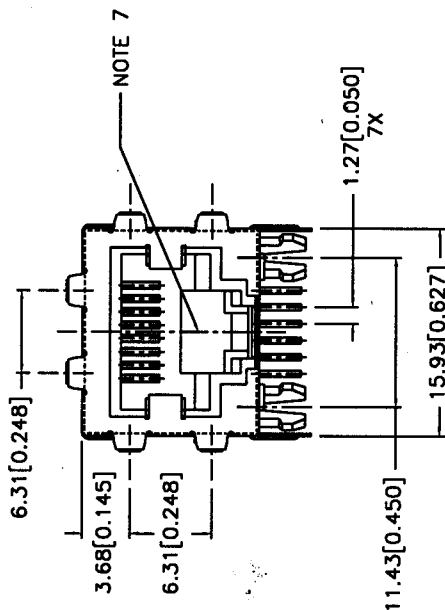




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mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY	title	www.ficconnect.com
ltr	ecn no	dr	date	linear	$\pm .3 / .XX \pm .01$	$XXX \pm .05 / XXXX \pm .0020$			
A	V80489	BWN	4/6/98			$XXX \pm .05 / XXXX \pm .0020$		RJ45 ENHANCED SHIELD PORT ASSY SNAP PEG	
B	V81781	RGD	10/9/98						
C	V90568	RGD	2/23/99	angles	$\sigma \pm Z$			product family size dwg no	code 213
D	V12591	LP	3/19/02	dr	R. GAPE 2/11/98				
E	M03-1103	PJ	10/17/03	engr	B. MARSHALL 2/11/98		scale 1:1	A	
F	M05-0068	MHT	4/15/05	chr	B. MARSHALL 2/11/98				
				opd	B. MARSHALL 2/11/98				
sheet	revision	F	F	F	F				
index	sheet	1	2	3	4				

PRODUCT NO.	SEE TABLE
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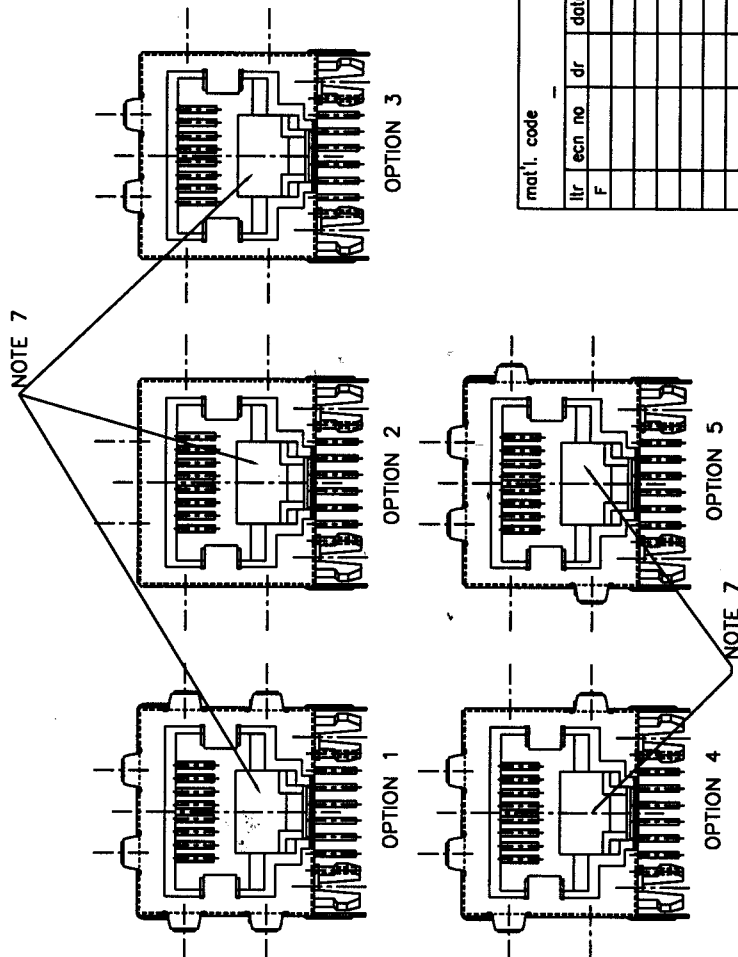
NOTE: PLEASE CHECK FOR AVAILABILITY, NOT ALL OPTIONS AVAILABLE.

PRODUCT NO	DIM A	DIM C	DIM F
74453-001XLF	3.05 [0.120]	N/A	1.02[0.040]
74453-002XLF	4.57 [0.179]	N/A	1.27[0.050]
74453-003XLF	N/A	3.05[0.120]	1.27[0.050]

SHIELD OPTION X	DESCRIPTION
1	SPRINGS ON TOP, BOTTOM AND SIDES
2	NO SPRINGS
3	SPRINGS ON TOP AND BOTTOM ONLY
4	SPRINGS ON TOP, BOTTOM AND 1 PER SIDE, STAGGERED
5	SAME AS OPTION 4 EXCEPT OPPOSITE STAGGER

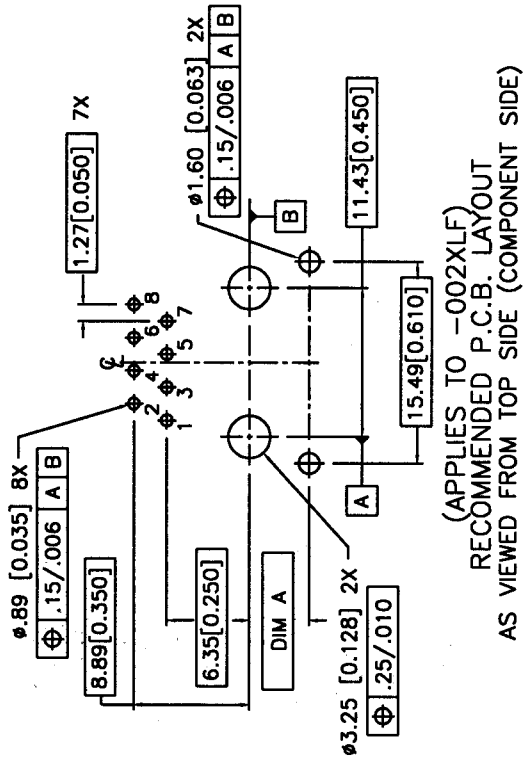
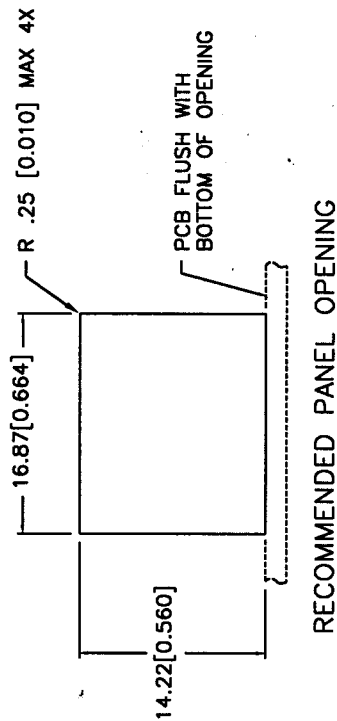
NOTES:

1. RECOMMENDED PCB THICKNESS 1.57 [0.062].
2. HOUSING MATL: HIGH TEMP. THERMOPLASTIC, COLOR BLACK, UL94V-0.
3. CONTACT MATL: COPPER ALLOY
4. MATING AREA PLATING: 1.27µm/50µ" MIN Au OVER Ni.
5. SOLDER AREA PLATING: 2.54µm/100µ" MIN TIN LEAD OVER Ni.
6. SHIELDING MATL: TIN PLATED COPPER ALLOY.
7. ALL DIMENSIONS IN MILLIMETERS AND INCHES.
8. DIMENSIONS AND TOLERANCES ARE IN ACCORDANCE WITH ASME Y14.5M 1994.
9. COMPANY LOGO LOCATED IN THIS AREA.
10. PART NUMBERS WITH LF IN THE END ARE LEAD FREE.
11. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AN OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008.
12. THE HOUSING TEMPERATURE WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 15 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.5 MM MINIMUM THICK CIRCUIT BOARD. SEE APPLICATION NOTES/PROCEDURES IF THEY ARE AVAILABLE.

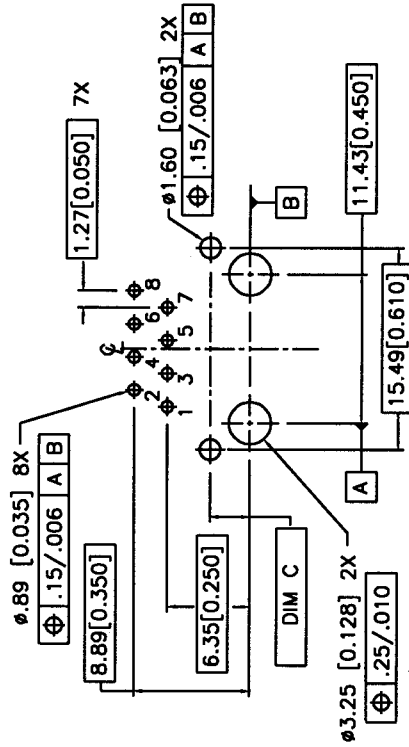
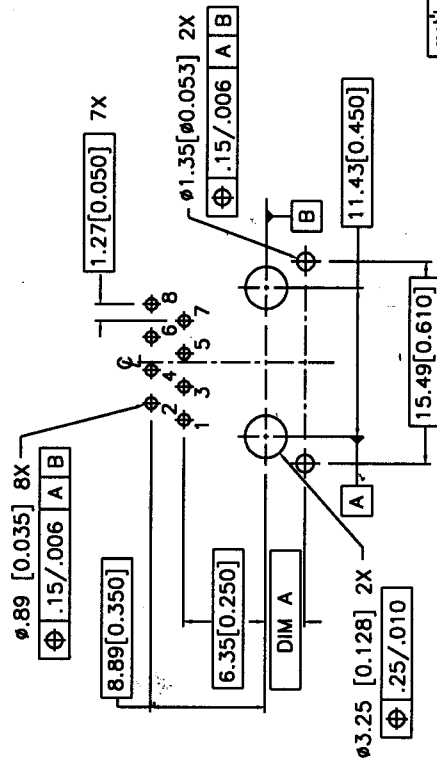


mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		FCI	
lfr	ecn no	dr	date	linear	angular	projection	title	product family	MOD JACK
F				$\pm 0.13 / \pm 0.05$	$\pm 0.051 / \pm 0.020$	$\phi \pm 0.020$	RJ45 ENHANCED SHIELD PORT ASSY SNAP PEG	code	213
				dr	R.GRAPE	2/11/98	MM/INCH	size	dwg no
				engr	B.MARSHALL	2/11/98	scale	A	74453
				chr	B.MARSHALL	2/11/98	1:1		
				opd	B.MARSHALL	2/11/98			
sheet	revision	sheet							
index									

PRODUCT NO.	SEE TABLE
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(APPLIES TO -002XLF)
RECOMMENDED P.C.B. LAYOUT
AS VIEWED FROM TOP SIDE (COMPONENT SIDE)



(APPLIES TO -003XLF)
RECOMMENDED P.C.B. LAYOUT
AS VIEWED FROM TOP SIDE (COMPONENT SIDE)

mat'l. code			tolerances unless otherwise specified			CUSTOMER COPY		FCJ		www.fcjconnect.com	
ltr	ecn no	dr	date	linear	.xx±.13/.xxx ±.01	projection		title		RJ45 ENHANCED SHIELD PORT ASSY SNAP PEG	
F					.xxx±.051/.xxx ±.0020			product family		MOD JACK	
				angles	0° ±2°			size (avg no		code	
				dr	R.GRAPE 2/11/98	MM/INCH		74453		213	
				enrg	B.WARSHALL 2/11/98	scale		A		sheet	
				chr	B.WARSHALL 2/11/98	1:1				3 of 4	
				apdd	B.WARSHALL 2/11/98						
sheet	revision										
index	sheet										





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2.49[0.098]

.37[0.015]

3.50[0.138]

3.95[0.156]

DIM A

DIM F

(APPLIES TO -001XLF AND -002XLF)

VIEW B

SCALE: 2/1

2.49[0.098]

.37[0.015]

3.50[0.138]

3.95[0.156]

DIM C

DIM F

(APPLIES TO -003XLF)

VIEW B

SCALE: 2/1

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

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[74453-0032LF](#)